

AMENDMENT AND RESPONSE UNDER 37 CFR § 1.116 - EXPEDITED PROCEDURE

Serial Number: 09/775366

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Title: ELECTRONIC DEVICE PACKAGE

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Dkt: 303.706US1IN THE SPECIFICATION

Please replace the paragraph starting at page 3, line 1 with the following paragraph:

Electronic packages, such as electronic package 101 and electronic package 125, are tested using a temperature cycle test. In a temperature cycle test, an electronic package, such as electronic package 101 or electronic package 125, is repeatedly heated and cooled. In one form of the temperature cycle test, electronic packaged packages 101 and 125 are repeatedly heated and cooled between minus 65 degrees Centigrade and 150 degrees Centigrade. Often this cyclic testing results in "cyclic strain" failures. These failures include separation of die attachment material 109 from die 103 and substrate 107 and deformation of die attachment material 109. Electronic packages that fail a "cyclic strain" test also often fail prematurely in the field.